

NL17SV32XV5T2

Single Gate 2-Input OR Gate

The NL17SV32 is an ultra-high performance 2 input OR gate manufactured in 0.35 μ CMOS technology with excellent performance down to 0.9 V. This device is ideal for extremely high-speed and high-drive applications. Additionally, limitations of board space are no longer a constraint. The very small SOT-553 makes this device fit most tight designs and spaces.

Features

- Extremely High Speed: $t_{PD} = 1.0$ ns (Typ) at $V_{CC} = 3.3$ V
- Designed for 0.9 to 3.3 V Operation
- Overvoltage Tolerance (OVT)* Input Pins Permit Logic Translation
- Balanced ± 24 mA Output Drive @ 3.3 V
- Near Zero Static Supply Current
- Ultra-Tiny SOT-553 5 Pin Package Only 1.6 x 1.6 x 0.6 mm
- These are Pb-Free Devices

Typical Applications

- Cellular
- Digital Camera
- PDA
- Digital Video

Important Information

- High ESD Ratings for Handling:
Human Body Model: 2000 V
Machine Model: 200 V
- Latchup Max Rating: 500 mA

Industry Standard

- Compatible with Fairchild's NC7SV32 and TI's SN74AUC1G32

FUNCTION TABLE

Input A	Input B	Output Y
L	L	L
L	H	H
H	L	H
H	H	H

*Overvoltage Tolerance (OVT) enables input pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.

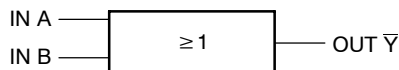


Figure 1. Logic Symbol



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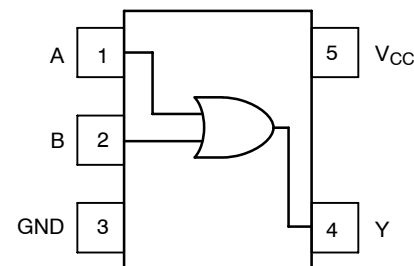
SOT-553
CASE 463B

MARKING DIAGRAM



UM = Device Code
M = Date Code*
A = Assembly Location
Y = Year
W = Work Week
■ = Pb-Free Package
(Note: Microdot may be in either location)

PIN DIAGRAM



PIN ASSIGNMENT

1	Input	A
2	Input	B
3	GND	-
4	Output	Y
5	V_{CC}	-

ORDERING INFORMATION

Device	Package	Shipping†
NL17SV32XV5T2	SOT-553*	4000 Tape & Reel
NL17SV32XV5T2G	SOT-553*	4000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

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MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to + 4.6	V
V _I	DC Input Voltage	-0.5 to + 4.6	V
V _O	DC Output Voltage	-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current V _I < GND	±50	mA
I _{OK}	DC Output Diode Current V _O = GND V _O = V _{CC}	-50 +50	mA
I _O	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current per Supply Pin	±50	mA
I _{GND}	DC Ground Current per Ground Pin	±50	mA
T _{STG}	Storage Temperature Range	- 65 to +150	°C
T _L	Lead Temperature, 1.0 mm from Case for 10 seconds	260	°C
T _J	Junction Temperature Under Bias	+150	°C
θ _{JA}	Thermal Resistance (Note 1)	250	°C/W
P _D	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen index: 28 to 34	UL 94 V-0 @ 0125 in	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	0.9	3.6	V
V _{IN}	Digital Input Voltage	0	3.6	V
V _{out}	Output Voltage	0	V _{CC}	V
I _{OH} /I _{OL}	Output Current V _{CC} = 3.0 V to 3.6 V V _{CC} = 2.3 V to 2.7 V V _{CC} = 1.65 V to 1.95 V V _{CC} = 1.4 V to 1.6 V V _{CC} = 1.1 V to 1.3 V V _{CC} = 0.9 V		±24 ±18 ±6 ±4 ±2 ±0.1	mA
t _A	Operating Temperature Range. All Package Types	-40	+85	°C
t _r , t _f	Input Rise or Fall Time V _{CC} = 3.3V ± 0.3 V	0	10	nS/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

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DC CHARACTERISTICS – Digital Section (Voltages Referenced to GND)

Symbol	Parameter	Condition	V _{CC}	T _A = 25°C		T _A = -40 to 85°C		Unit	
				Min	Max	Min	Max		
V _{IH}	High Level Input Voltage		0.90	0.65 x V _{CC}		0.65 x V _{CC}		V	
			1.10 ≤ V _{CC} ≤ 1.30	0.65 x V _{CC}		0.65 x V _{CC}			
			1.40 ≤ V _{CC} ≤ 1.60	0.65 x V _{CC}		0.65 x V _{CC}			
			1.65 ≤ V _{CC} ≤ 1.95	0.65 x V _{CC}		0.65 x V _{CC}			
			2.30 ≤ V _{CC} ≤ 2.70	1.6		1.6			
2.70 ≤ V _{CC} ≤ 3.60	2.0		2.0						
V _{IL}	Low Level Input Voltage		0.90		0.35 x V _{CC}		0.35 x V _{CC}	V	
			1.10 ≤ V _{CC} ≤ 1.30		0.35 x V _{CC}		0.35 x V _{CC}		
			1.40 ≤ V _{CC} ≤ 1.60		0.35 x V _{CC}		0.35 x V _{CC}		
			1.65 ≤ V _{CC} ≤ 1.95		0.35 x V _{CC}		0.35 x V _{CC}		
			2.30 ≤ V _{CC} ≤ 2.70		0.7		0.7		
2.70 ≤ V _{CC} ≤ 3.60		0.8		0.8					
V _{OH}	High Level Output Voltage	I _{OH} = -100 μA	0.90	V _{CC} - 0.1		V _{CC} - 0.1		V	
			1.10 ≤ V _{CC} ≤ 1.30	V _{CC} - 0.1		V _{CC} - 0.1			
			1.40 ≤ V _{CC} ≤ 1.60	V _{CC} - 0.2		V _{CC} - 0.2			
			1.65 ≤ V _{CC} ≤ 1.95	V _{CC} - 0.2		V _{CC} - 0.2			
			2.30 ≤ V _{CC} ≤ 2.70	V _{CC} - 0.2		V _{CC} - 0.2			
			2.70 ≤ V _{CC} ≤ 3.60	V _{CC} - 0.2		V _{CC} - 0.2			
			I _{OH} = -2.0 mA	1.10 ≤ V _{CC} ≤ 1.30	0.75 x V _{CC}		0.75 x V _{CC}		
I _{OH} = -4.0 mA	1.40 ≤ V _{CC} ≤ 1.60	0.75 x V _{CC}		0.75 x V _{CC}					
I _{OH} = -6.0 mA	1.65 ≤ V _{CC} ≤ 1.95	2.30 ≤ V _{CC} ≤ 2.70	1.25		1.25				
			2.0		2.0				
I _{OH} = -12 mA	2.30 ≤ V _{CC} ≤ 2.70	2.70 ≤ V _{CC} ≤ 3.60	1.8		1.8				
			2.2		2.2				
I _{OH} = -18 mA	2.30 ≤ V _{CC} ≤ 2.70	2.70 ≤ V _{CC} ≤ 3.60	1.7		1.7				
			2.4		2.4				
I _{OH} = -24 mA	2.70 ≤ V _{CC} ≤ 3.60		2.2		2.2				
V _{OL}	Low Level Output Voltage	I _{OL} = 100 μA	0.90		0.1		0.1	V	
			1.10 ≤ V _{CC} ≤ 1.30		0.1		0.1		
			1.40 ≤ V _{CC} ≤ 1.60		0.2		0.2		
			1.65 ≤ V _{CC} ≤ 1.95		0.2		0.2		
			2.30 ≤ V _{CC} ≤ 2.70		0.2		0.2		
			2.70 ≤ V _{CC} ≤ 3.60		0.2		0.2		
			I _{OL} = 2.0 mA	1.10 ≤ V _{CC} ≤ 1.30		0.25 x V _{CC}			0.25 x V _{CC}
			I _{OL} = 4.0 mA	1.40 ≤ V _{CC} ≤ 1.60		0.25 x V _{CC}			0.25 x V _{CC}
I _{OL} = 6.0 mA	1.65 ≤ V _{CC} ≤ 1.95	2.30 ≤ V _{CC} ≤ 2.70	2.70 ≤ V _{CC} ≤ 3.60	0.3		0.3			
				0.3		0.3			
I _{OL} = 12 mA	2.30 ≤ V _{CC} ≤ 2.70	2.70 ≤ V _{CC} ≤ 3.60	0.4		0.4				
			0.4		0.4				
I _{OL} = 18 mA	2.30 ≤ V _{CC} ≤ 2.70	2.70 ≤ V _{CC} ≤ 3.60	0.6		0.6				
			0.4		0.4				
I _{OL} = 24 mA	2.70 ≤ V _{CC} ≤ 3.60		0.55		0.55				
I _{IN}	Input Leakage Current	0 = V _I = 3.6 V	0.90 to 3.60		±0.1		±0.9	μA	
I _{OFF}	Power Off Leakage Current		0		1		5	μA	
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	0.90 to 3.60		0.9		5	μA	

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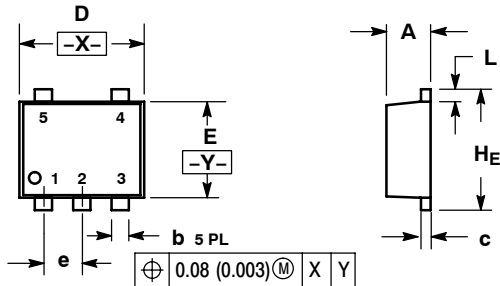
AC CHARACTERISTICS (Input $t_r = t_f = 3.0$ nS)

Symbol	Parameter	-40°C		25°C			85°C		Unit
		Condition	V _{CC}	Min	Typ	Max	Min	Max	
T _{PHL} , T _{PLH}	Propagation Delay	C _L = 15 pF, R _L = 1.0 MΩ	0.90		13				nS
		C _L = 15 pF, R _L = 2.0 kΩ	1.10 ≤ V _{CC} ≤ 1.30	3.0	6.0	15.8	1.0	18.6	nS
			1.40 ≤ V _{CC} ≤ 1.60	1.0	3.2	8.7	1.0	9.7	
C _L = 30 pF, R _L = 500 kΩ	1.65 ≤ V _{CC} ≤ 1.95	1.0	2.0	6.0	1.0	6.8	nS		
		2.30 ≤ V _{CC} ≤ 2.70	0.8	1.2	4.1	0.7		4.7	
		2.70 ≤ V _{CC} ≤ 3.60	0.7	1.0	3.3	0.6		4.0	
C _{IN}	Input Capacitance		0		2.0				pF
C _{OUT}	Output Capacitance		0		4.5				pF
C _{PD}	Power Dissipation Capacitance	V _I = 0 V or V _{CC} F = 10 MHz	0.90 to 3.60		20				pF

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PACKAGE DIMENSIONS

SOT-553, 5 LEAD
CASE 463B-01
ISSUE B

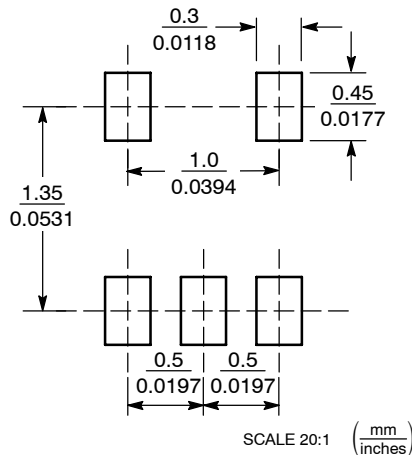


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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